



Device Material Content

5555 NE Moore Ct. Hillsboro OR 97124 custreq@latticesemi.com		Package: 256 ftBGA Total Device Weight 854.2 mg			Package Code: <div style="border: 1px solid black; padding: 2px; display: inline-block;">FTG256</div>		Assembly: ASEK Size (mm): 17 x 17 Lead pitch (mm): 1.0 MSL: 3 Reflow max (°C): 260		
March, 2026					Products: <div style="border: 1px solid black; padding: 2px; display: inline-block;">XO3D</div>				
	% of Total Pkg. Wt.	Weight (mg)	% of Total Pkg. Wt.	Weight (mg)	Substance	CAS #	% of Subst.	Notes / Assumptions:	
Die	1.215%	10.379	1.215%	10.3793	Silicon chip	7440-21-3	100.00%	Die size: 3.95 x 5.55 mm	
Mold Compound	64.069%	547.259	48.391%	413.3376	Aluminum oxide	1344-28-1	75.53%	Kyocera KE-G1250AHT	
			6.452%	55.1117	Silica(Fused)(1)	60676-86-0	10.07%		
			3.549%	30.3114	Silica(Fused)(2)	7631-86-9	5.54%		
			3.549%	30.3114	Epoxy resin	TRADE SECRET	5.54%		
			1.936%	16.5335	Phenol resin	TRADE SECRET	3.02%		
			0.194%	1.6534	Carbon Black	1333-86-4	0.30%		
D/A Epoxy	0.44%	3.7425	0.377%	3.22191	Silver (Ag)	7440-22-4	86.09%	Henkel (Ablebond) 2100A	
			0.026%	0.22156	2,2-dimethyl-1,3 Propanediyl Bismethacrylate	1985-51-9	5.92%		
			0.022%	0.18413	A mixture of: 4-allyl-2,6-bis(2,3-epoxypropyl)phenol	-	4.92%		
			0.004%	0.03742	Perfluoropolyoxyalkane ether	925918-64-5	1.00%		
			0.008%	0.07036	2-[[[2 bis[[[(1-oxoallyl)oxy]methyl]butoxy]methyl]-2-ethyl-1,3-propanediyl diacrylate	94108-97-1	1.88%		
			0.001%	0.00711	bis(4-tert-butylcyclohexyl) peroxydicarbonate	15520-11-3	0.19%		
Wire	0.26%	2.2290	0.26%	2.1905	Copper	7440-50-8	98.28%	0.8 mil diameter; 1 wire per solder ball NMC EX1P+_CuPdAu+	
			0.004%	0.0345	Palladium	2023568	1.55%		
			0.0005%	0.0039	Gold	7440-57-5	0.18%		
Solder Balls	11.49%	98.1608	11.08%	94.6761	Tin	7440-31-5	96.45%	96.45SN/3.0AG/0.5CU/0.05NI_0.5MM PMT	
			0.34%	2.9448	Silver	7440-22-4	3.00%		
			0.06%	0.4908	Copper	7440-50-8	0.50%		
			0.01%	0.0491	Nickel	7440-02-0	0.05%		
Substrate	22.52%	192.40	0.28%	2.4214	Barium Sulfate	7727-43-7	1.26%	CCL-HL832NX (Type A) PSR-800 AUS SR1	
			0.09%	0.8071	Silica	7631-86-9	0.42%		
			0.03%	0.2421	Talc	14807-96-6	0.13%		
			0.51%	4.3586	Epoxy Resin	85954-11-6	2.27%		
			0.03%	0.2421	Phosphin oxide derivative	Trade secret	0.13%		
			4.47%	38.1480	Continuous Filament Fiber Glass	65997-17-3	19.83%		
			7.31%	62.4240	Bismaleimide Triazine , Epoxy Resin	105391-33-1	32.45%		
			1.76%	15.0280	Inorganic filler	25722-66-1	7.81%		
			2.72%	23.2155	Copper	9003-36-5	12.07%		
			4.76%	40.6272	Copper	21645-51-2	21.12%		
			0.48%	4.0851	Nickel	7440-50-8	2.12%		
			0.09%	0.7973	Gold	7440-02-0	2.12%		
					Gold	7440-57-5	0.41%		

Note:

Lattice regards this materials information to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Lattice subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers ("Contractors"). All data provided hereunder is based on information received from Contractors. Lattice has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Lattice products.

www.latticesemi.com

